

Abstract of the Disclosure

In an embedding resin for embedding electronic parts, after a substrate in which a copper layer is formed on a cured product of the embedding resin is subjected to a pressure cooker test, the copper layer has a peeling strength of at least 588 N/m (0.6 kg/cm), wherein the conditions of the pressure cooker test are 121°C, 100% by mass humidity, 2.1 atm and 168 hours, and the measurement method of the peeling strength is according to JIS C 5012, and the width of the copper layer is 10 mm.

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